

/ Revised record

D	2017-5				
E	2021-1-27	4/7	0.5-0.8	e0.5-0.7 5 7	

/ Descriptions

0.5A

MBF

0.5A Surface Mount Glass Passivated Bridge Rectifier, MBF thin package.

/ Features

100V~1000V

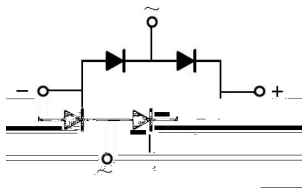
0.5A

Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current: 0.5A, High Surge Current Capability, Designed for Surface Mount Application, Halogen free product.

/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

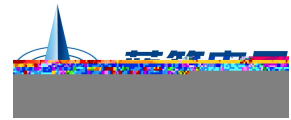


/ Marking

See Marking Instructions.

MB1F-05~MB10F-05

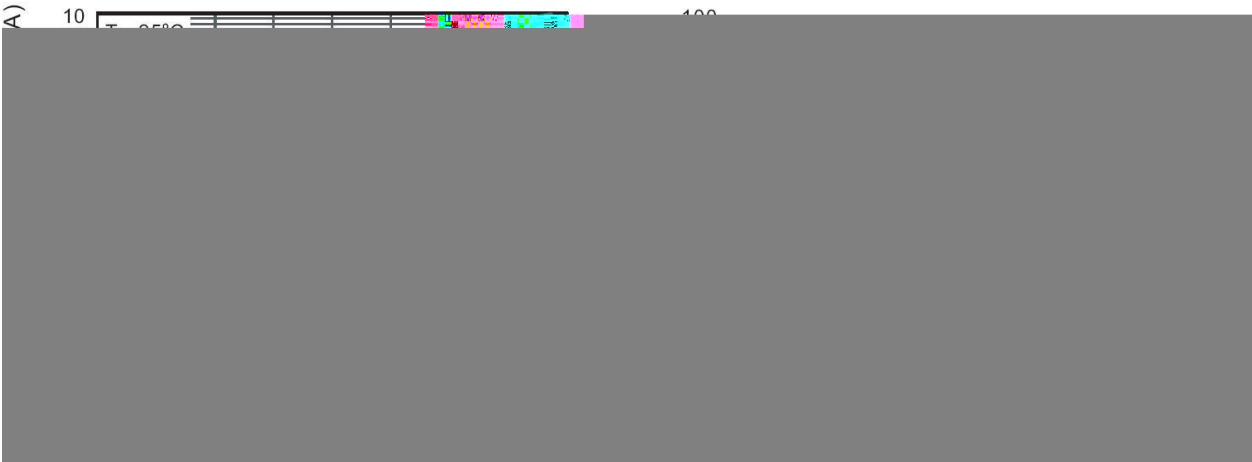
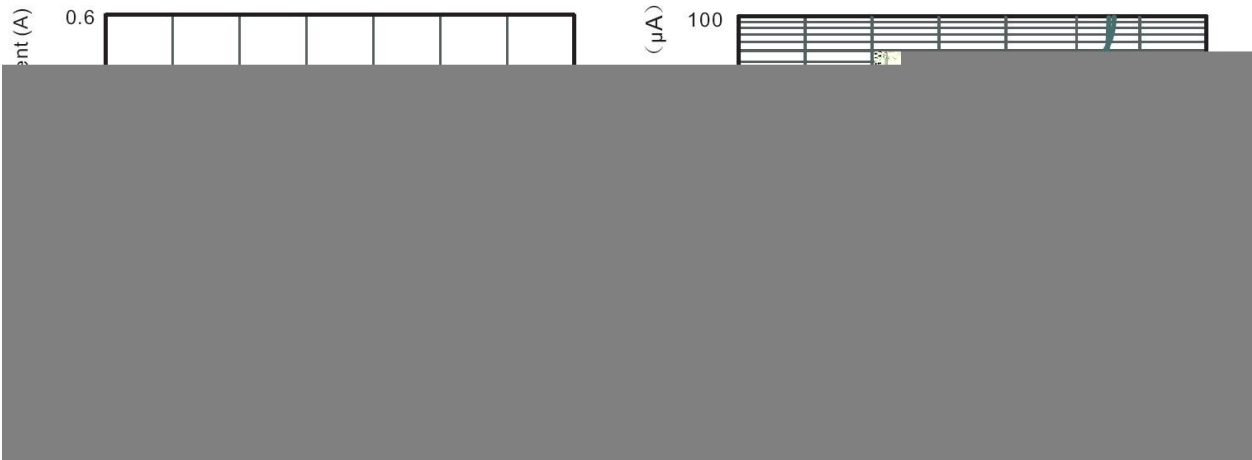
Rev.E Jan.-2021



DATA SHEET

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		MB1F-05	MB2F-05	MB4F-05	MB6F-05	MB8F-05	MB10F-05	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V

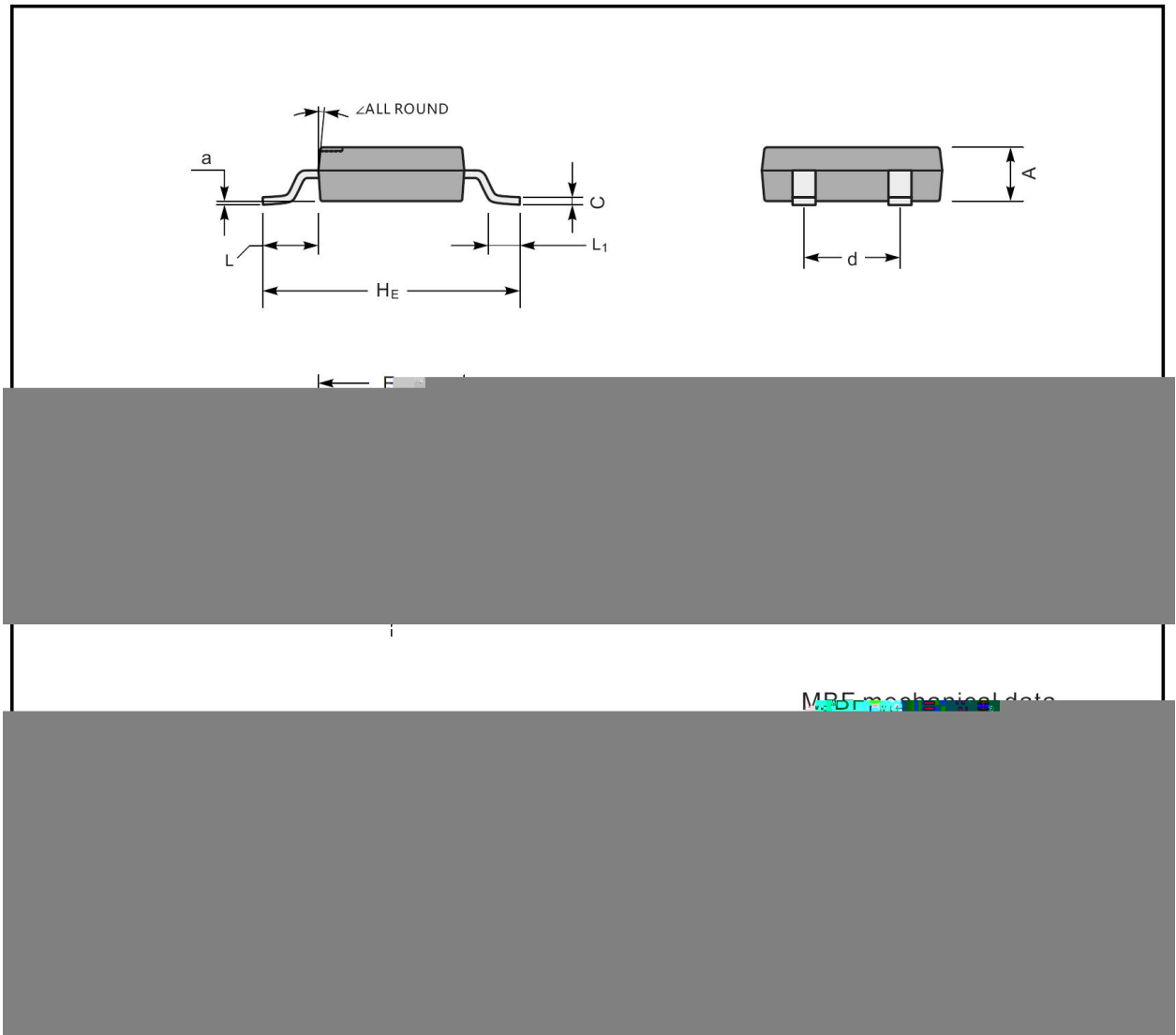
/ Electrical Characteristic Curve





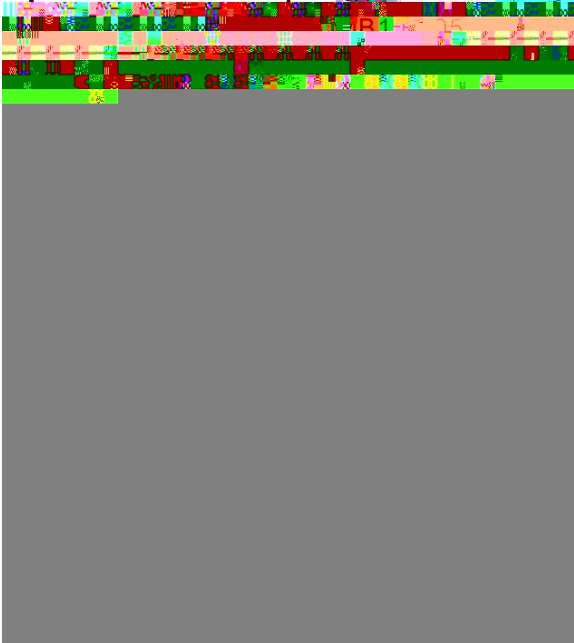
/ Package Dimensions

MBF

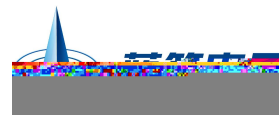


/ Marking Instructions

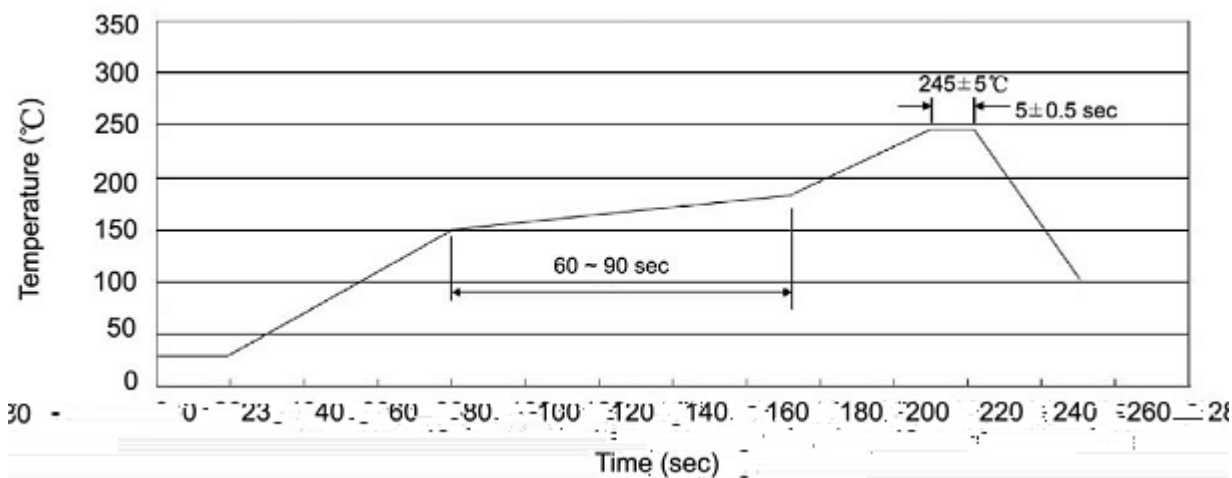
Marking

Type number	Marking code
	

MB1F



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
MBF	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

/ Notices